**URL** for Additional Information

PART INFORMATION

Mfg Item Number

Mfg Item Name

MCIMX6Q6AVT10AD

FC-PBGA 624 21\*21\*2 P0.8

SUPPLIER Company Name Freescale Semiconductor Inc Company Unique ID 14-141-7928 Response Date 2013-09-11 Response Document ID 00A2K10737D169M1.0 Contact Name Freescale Semiconductor Inc Contact Title Product Technical Support **Contact Phone** 1-800-521-6274 Contact Email support@freescale.com **Authorized Representative** Daniel Binyon Representative Title **EPP Customer Response** Representative Phone 512-895-3406 Representative Email eppanlst@freescale.com

DECLARATION

EU RoHS
Pb Free
HalogenFree
Plating Indicator
EU RoHS Exemption(s)

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MANUFACTURING Mfg Item Number MCIMX6Q6AVT10AD Mfg Item Name FC-PBGA 624 21\*21\*2 P0.8 Version ALL Weight 3.323600 UoM Unit Volume EACH J-STD-020 MSL Rating 3 Peak Processing Temperature 260 C Max Time at Peak Temperature 40 seconds Number of Processing Cycles 3

2011/65/EU **RoHS Directive** RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium **RoHS Definition** Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess **RoHS Legal Definition** restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply. Sale applicable to such part(s) shall apply. **RoHS Declaration** 1 - Item(s) do not contain RoHS restricted substances per the definition above Accepted Supplier Acceptance Signature **Daniel Binyon** Exemptions in this part List of Freescale Accepted Exemptions 6(a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b): Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c): Copper alloy containing up to 4% lead by weight 7(a): Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for 7(c)-1: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV: Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors

15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

| SubPart                        | Weight | SubstanceClass                           | Substance   | CAS        | Exemption | SubstanceWeight | UoM | SubPart<br>PPM | SubPart% | REACHPPM | REACH%  |
|--------------------------------|--------|--|---|------------|-----------|-----------------|-----|----------------|----------|----------|---------|
| Organic Substrate, Halogen-fre | 0.9169 |  |   |            |           |                 | g   |                |          |          |         |
| Organic Substrate, Halogen-fre |        | Metals                                   | Barium sulfate  | 7727-43-7  |           | 0.009758        | g   | 10642          | 1.0642   | 2935     | 0.2935  |
| Organic Substrate, Halogen-fre |        | Metals                                   | Copper, metal   | 7440-50-8  |           | 0.562946        | g   | 613967         | 61.3967  | 169381   | 16.9381 |
| Organic Substrate, Halogen-fre |        | Solvents, additives, and other materials | Other imidazole compounds   | -          |           | 0.000557        | g   | 608            | 0.0608   | 167      | 0.0167  |
| Organic Substrate, Halogen-fre |        | Metals                                   | Talc  | 14807-96-6 |           | 0.001672        | g   | 1824           | 0.1824   | 503      | 0.0503  |
| Organic Substrate, Halogen-fre |        | Solvents, additives, and other materials | Other organic Silicon Compounds                                   | -          |           | 0.001765        | g   | 1925           | 0.1925   | 531      | 0.0531  |
| Organic Substrate, Halogen-fre |        | Solvents, additives, and other materials | Proprietary Material-Other organic silicon compounds              | -          |           | 0.065233        | g   | 71145          | 7.1145   | 19627    | 1.9627  |
| Organic Substrate, Halogen-fre |        | Plastics/polymers                        | 4,4'-Isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate | 25068-38-6 |           | 0.009107        | g   | 9932           | 0.9932   | 2740     | 0.274   |
| Organic Substrate, Halogen-fre |        | Glass                                    | Fibrous-glass-wool  | 65997-17-3 |           | 0.182318        | g   | 198842         | 19.8842  | 54856    | 5.4856  |
| Organic Substrate, Halogen-fre |        | Glass                                    | Silicon dioxide   | 7631-86-9  |           | 0.059231        | g   | 64599          | 6.4599   | 17821    | 1.7821  |
| Organic Substrate, Halogen-fre |        | Glass                                    | Other silica compounds  | -          |           | 0.001765        | g   | 1925           | 0.1925   | 531      | 0.0531  |
| Organic Substrate, Halogen-fre |        | Metals                                   | Silver, metal   | 7440-22-4  |           | 0.000055        | g   | 60             | 0.006    | 16       | 0.0016  |
| Organic Substrate, Halogen-fre |        | Metals                                   | Tin, metal  | 7440-31-5  |           | 0.001837        | g   | 2003           | 0.2003   | 552      | 0.0552  |
| Organic Substrate, Halogen-fre |        | Solvents, additives, and other materials | Toluene   | 108-88-3   |           | 0.000176        | g   | 192            | 0.0192   | 52       | 0.0052  |
| Organic Substrate, Halogen-fre |        | Plastics/polymers                        | Other Non-halogenated Epoxy resins                                | -          |           | 0.016726        | g   | 18242          | 1.8242   | 5032     | 0.5032  |
| Organic Substrate, Halogen-fre |        | Solvents, additives, and other materials | Other organosilane compounds                                      | -          |           | 0.000093        | g   | 101            | 0.0101   | 27       | 0.0027  |
| Organic Substrate, Halogen-fre |        | Solvents, additives, and other materials | Cyclohexanone   | 108-94-1   |           | 0.003661        | g   | 3993           | 0.3993   | 1101     | 0.1101  |
| Underfill                      | 0.012  |  |   |            |           |                 | g   |                |          |          |         |
| Underfill                      |        | Metals                                   | Other bismuth compounds   | -          |           | 0.000299        | g   | 24876          | 2.4876   | 89       | 0.0089  |
| Underfill                      |        | Plastics/polymers                        | 1,6-Bis(2,3-epoxypropoxy) naphthalene                             | 27610-48-6 |           | 0.001791        | g   | 149254         | 14.9254  | 538      | 0.0538  |
| Underfill                      |        | Plastics/polymers                        | Phenolic Polymer Resin, Epikote 155                               | 9003-36-5  |           | 0.001194        | g   | 99502          | 9.9502   | 359      | 0.0359  |
| Underfill                      |        | Solvents, additives, and other materials | Carbon Black  | 1333-86-4  |           | 0.00006         | g   | 4975           | 0.4975   | 18       | 0.0018  |
| Underfill                      |        | Plastics/polymers                        | 4,4'-Isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate | 25068-38-6 |           | 0.000299        | g   | 24876          | 2.4876   | 89       | 0.0089  |
| Underfill                      |        | Glass                                    | Silica, vitreous  | 60676-86-0 |           | 0.007163        | g   | 597015         | 59.7015  | 2155     | 0.2155  |
| Underfill                      |        | Solvents, additives, and other materials | Diethyltoluenediamine   | 68479-98-1 |           | 0.001194        | g   | 99502          | 9.9502   | 359      | 0.0359  |
| Epoxy Die Attach               | 0.0097 |  |   |            |           |                 | g   |                |          |          |         |
| Epoxy Die Attach               |        | Metals                                   | Aluminum Oxides (Al2O3)   | 1344-28-1  |           | 0.00776         | g   | 800000         | 80       | 2334     | 0.2334  |
| Epoxy Die Attach               |        | Solvents, additives, and other materials | Siloxanes and silicones, di-Me, vinyl group-terminated            | 68083-19-2 |           | 0.00194         | g   | 200000         | 20       | 583      | 0.0583  |
| Solder Balls - Lead Free       | 0.3172 |  |   |            |           |                 | g   |                |          |          |         |
| Solder Balls - Lead Free       |        | Metals                                   | Copper, metal   | 7440-50-8  |           | 0.001589        | g   | 5009           | 0.5009   | 478      | 0.0478  |
| Solder Balls - Lead Free       |        | Metals                                   | Silver, metal   | 7440-22-4  |           | 0.009533        | g   | 30054          | 3.0054   | 2868     | 0.2868  |
| Solder Balls - Lead Free       |        | Metals                                   | Tin, metal  | 7440-31-5  |           | 0.306078        | g   | 964937         | 96.4937  | 92093    | 9.2093  |
| Gel Die Encapsulant            | 0.0206 |  |   |            |           |                 | g   |                |          |          |         |
| Gel Die Encapsulant            |        | Metals                                   | Aluminum, metal   | 7429-90-5  |           | 0.01442         | g   | 699968         | 69.9968  | 4338     | 0.4338  |
| Gel Die Encapsulant            |        | Solvents, additives, and other materials | Other organic Silicon Compounds                                   | -          |           | 0.00205         | g   | 99510          | 9.951    | 616      | 0.0616  |
| Gel Die Encapsulant            |        | Metals                                   | Zinc oxide  | 1314-13-2  |           | 0.00412         | g   | 200022         | 20.0022  | 1239     | 0.1239  |
| Gel Die Encapsulant            |        | Plastics/polymers                        | Other non-halogenated polymers                                    | -          |           | 0.00001         | g   | 500            | 0.05     | 3        | 0.0003  |
| Heat Spreader                  | 2.0062 |  |   |            |           |                 | g   |                |          |          |         |
| Heat Spreader                  |        | Metals                                   | Copper, metal   | 7440-50-8  |           | 1.975038        | g   | 984467         | 98.4467  | 594260   | 59.426  |
| Heat Spreader                  |        | Metals                                   | Nickel, metal   | 7440-02-0  |           | 0.031162        | g   | 15533          | 1.5533   | 9375     | 0.9375  |
| Pb-free Bumped Semiconductor D | 0.041  |  |   |            |           |                 | g   |                |          |          |         |
| Pb-free Bumped Semiconductor D |        | Metals                                   | Nickel, metal   | 7440-02-0  |           | 0.000205        | g   | 5000           | 0.5      | 61       | 0.0061  |
| Pb-free Bumped Semiconductor D |        | Metals                                   | Silver, metal   | 7440-22-4  |           | 0.000129        | g   | 3150           | 0.315    | 38       | 0.0038  |
| Pb-free Bumped Semiconductor D |        | Metals                                   | Tin, metal  | 7440-31-5  |           | 0.003561        | g   | 86850          | 8.685    | 1071     | 0.1071  |
| Pb-free Bumped Semiconductor D |        | Solvents, additives, and other materials | Other miscellaneous substances (less than 5%).                    | -          |           | 0.000369        | g   | 9000           | 0.9      | 111      | 0.0111  |
| Pb-free Bumped Semiconductor D |        | Glass                                    | Silicon, doped  | -          |           | 0.036736        | g   | 896000         | 89.6     | 11053    | 1.1053  |

LINKS

MCD LINK

http://www.freescale.com Freescale website

GENERAL ENVIRONMENTAL COMPLIANCE LINKS

http://www.freescale.com/files/abstract/corporate/ehs\_epp/ENV\_ROHS\_Freescale\_Response.pdf

RoHS signed letter China RoHS http://www.freescale.com/chinarohs

REACH signed letter http://www.freescale.com/files/abstract/corporate/ehs\_epp/ENV\_REACH\_Freescale\_Response.pdf http://www.freescale.com/files/abstract/corporate/ehs\_epp/ENV\_ELV\_Freescale\_Reponse.pdf ELV signed letter

http://www.freescale.com/files/abstract/corporate/ehs\_epp/ENV\_CONFLICT\_METAL\_Freescale\_Response.pdf Conflict Minerals statement FREESCALE ENVIRONMENTAL INFORMATION

EPP website

http://www.freescale.com/epp

FAQ

**Technical Service Request** 

LINKS TO BLANK IPC1752 FORMS

http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON\_FAQ

https://www.freescale.com/webapp/servicerequest.create\_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod

Blank IPC1752 v0.9 Form  $http://www.freescale.com/files/abstract/corporate/ehs\_epp/IPC-1752-2\_v0.9\_MCD\_Template.pdf$ http://www.freescale.com/files/abstract/corporate/ehs\_epp/IPC-1752-2\_v1.1\_MCD\_Template.pdf Blank IPC1752 v1.1 Form

## IPC1752 XML LINKS

http://www.freescale.com/mcds/MCIMX6Q6AVT10AD\_IPC1752\_v09.xml

http://www.freescale.com/mcds/MCIMX6Q6AVT10AD\_IPC1752\_v11.xml

http://www.freescale.com/mcds/MCIMX6Q6AVT10AD\_IPC1752A.xml